| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| S1 | 1025 | 361/792.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 09:32 |
| S2 | 105 | S1 and (organic and ceramic) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 09:32 |
| S3 | 3850 | 361/762,761,764,795,792.ccls. or 174/256,258.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 09:55 |
| S4 | 553 | S3 and organic and ceramic | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 09:55 |
| S5 | 55 | S3 and (heatsink or heat$sink) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 09:57 |
| S6 | 6 | S4 and (heatsink or heat$sink) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 10:01 |
| S7 | 4 | "6180436".pn. "6365964".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 10:01 |
| S8 | 1161 | (ceramic near substrate) and (organic near substrate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 10:14 |

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|------|------|---------------------------------------------------------------------------|-------------------------------------------------|----|----|---------------------|
| S9 | 603 | S8 and (pcb or "circuit board") | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/04 10:59 |
| S10 | 0 | 174/255-259,252 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/04 11:00 |
| S11 | 4356 | 174/255-259,252.ccls. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/04 11:01 |
| S12 | 2322 | S11 and (cermanic or non$organic "metal oxide" "metal nitride" oxide nitride organic plastic) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/04 11:26 |
| S13 | 1730 | S12 and substrate | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/04 11:12 |
| S14 | 1411 | S13 and (conductor or wire or trace) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/04 11:12 |
| S15 | 1231 | S14 and @pd<"20040401" | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/04 11:27 |
| S16 | 824 | S11 and (cermanic or non$organic "metal oxide" "metal nitride" oxide nitride ) and (organic plastic) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/04 11:27 |

| S17 | 720 | S16 and @pd<"20040401" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 11:27 |
|---|---|---|---|---|---|---|
| S18 | 581 | S17 and (conductor wire trace) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 11:36 |
| S19 | 0 | (ceramic and organi).ti. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 11:36 |
| S20 | 2866 | (ceramic and organic).ti. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 11:36 |
| S21 | 434 | S20 and substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 11:42 |
| S22 | 28 | S21 and (pcb or "circuit board") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 11:37 |
| S23 | 5481 | (organic with ceramic with substrate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 11:42 |
| S24 | 574 | S23 same (pcb or "circuit board") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/05 08:33 |

| S25 | 5788 | 428/209,210,901.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 14:25 |
|-----|------|-----------------------|---------------------------------------------------|-----|-----|-------------------|
| S26 | 455 | S25 and (ceramic with organic) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/04 14:28 |
| S27 | 763999 | chip | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/05 08:14 |
| S28 | 27 | ("5036431" \| "5311402" \| "5481435" \| "5614766").PN. OR ("5936843").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/10/05 08:23 |
| S29 | 20 | ("5072075" \| "5483421" \| "5491303" \| "5574630" \| "5615087" \| "5689091" \| "5808873" \| "5815374" \| "5894173" \| "5900675" \| "5936843" \| "5962922" \| "6137062" \| "6162997" \| "6163462" \| "6239980" \| "6271478" \| "6288347" \| "6335495").PN. OR ("6538213").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/10/05 08:28 |
| S30 | 5481 | (organic with ceramic with substrate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/05 08:34 |
| S31 | 574 | S30 same (pcb or "circuit board") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/05 08:34 |
| S32 | 450 | S31 and component | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/05 08:43 |

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|---|---|---|---|---|---|---|
| S33 | 116 | S31 same component | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/05 08:38 |
| S34 | 1223090 | S32 amd (traces or conductor) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/05 08:43 |
| S35 | 321 | S32 and (traces or conductor) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/05 08:57 |
| S36 | 5788 | 428/209,210,901.ccls. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/05 08:57 |
| S37 | 175 | S36 and S30 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/05 08:57 |
| S38 | 23 | ("4680220" \| "4810563" \|<br>"4849284" \| "4882455" \| "5061548"<br>\| "5139852" \| "5213878" \|<br>"5277725" \| "5287619" \| "5358775"<br>\| "5384181" \| "5541249" \|<br>"5552210" \| "5571609" \| "5670262"<br>\| "5733640" \| "5919546" \|<br>"5922453" \| "5965273").PN. OR<br>("6528145").URPN. | US-PGPUB;<br>USPAT;<br>USOCR | OR | ON | 2005/10/05 08:58 |
| S39 | 4 | "power integrated circuit chip" with<br>"ceramic substrate" | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/05 09:35 |
| S40 | 0 | 10/708935 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/05 09:47 |

| S41 | 0 | "10708935" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/05 09:47 |
|-----|---|------------|-----|----|----|------|
| S42 | 0 | "10/708935" | US-PGPUB | OR | ON | 2005/10/05 09:48 |
| S43 | 15 | oman.inv. | US-PGPUB | OR | ON | 2005/10/05 09:49 |
| S44 | 8 | degenkolb.inv. | US-PGPUB | OR | ON | 2005/10/05 09:49 |
| S45 | 9298479 | (ceramic near substrate) with (organic near substrate) wit (adjacent or beside or parallel or connected) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/05 10:27 |
| S46 | 6 | (ceramic near substrate) with (organic near substrate) with (adjacent or beside or parallel or connected) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/05 10:27 |